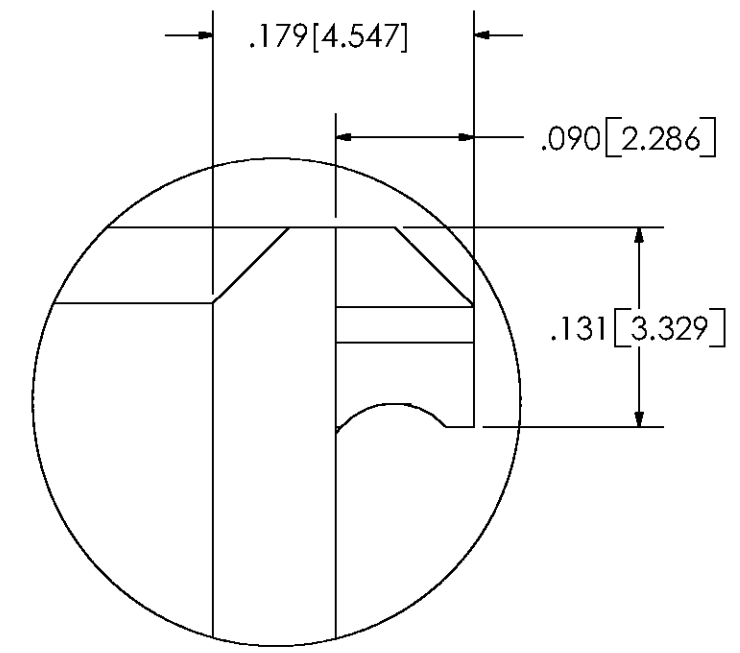
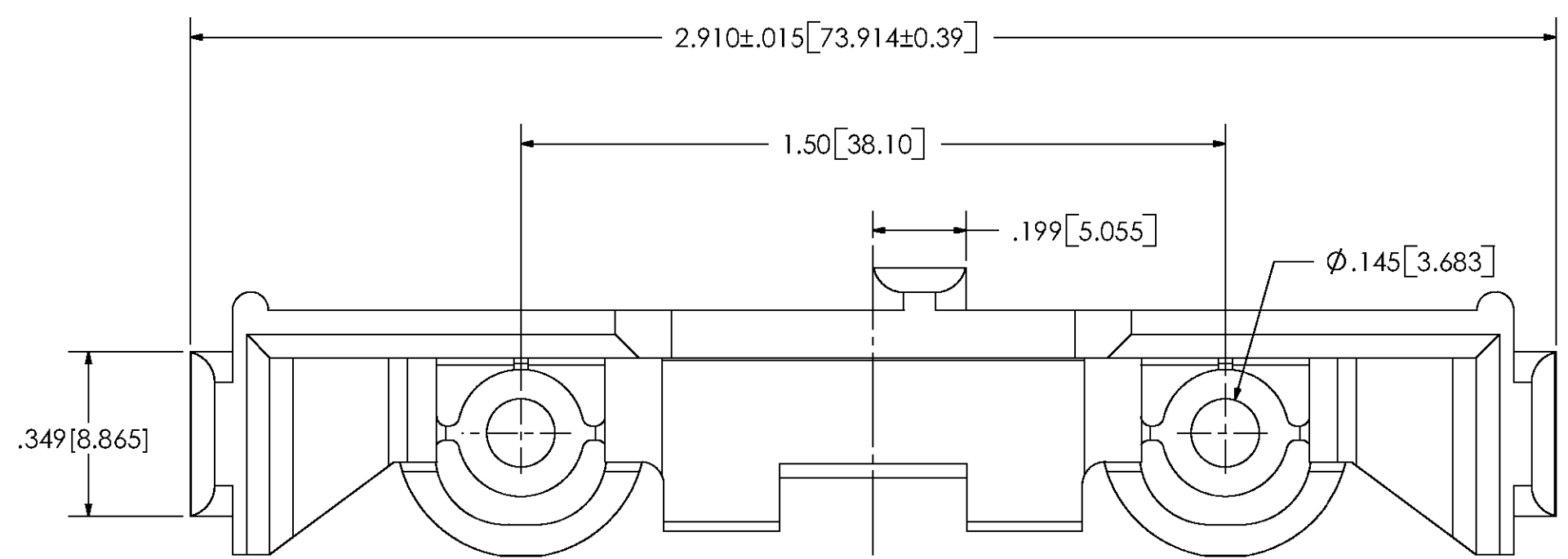
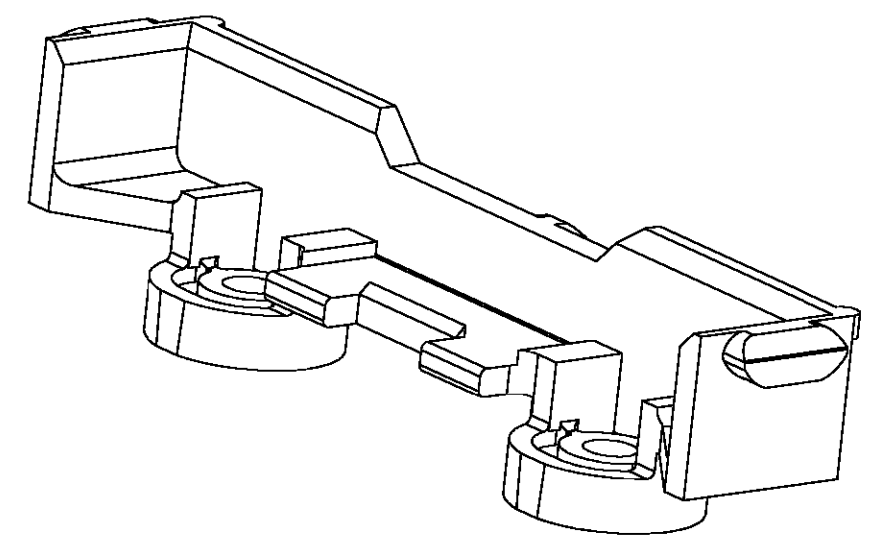


8 7 6 5 4 3 2 1

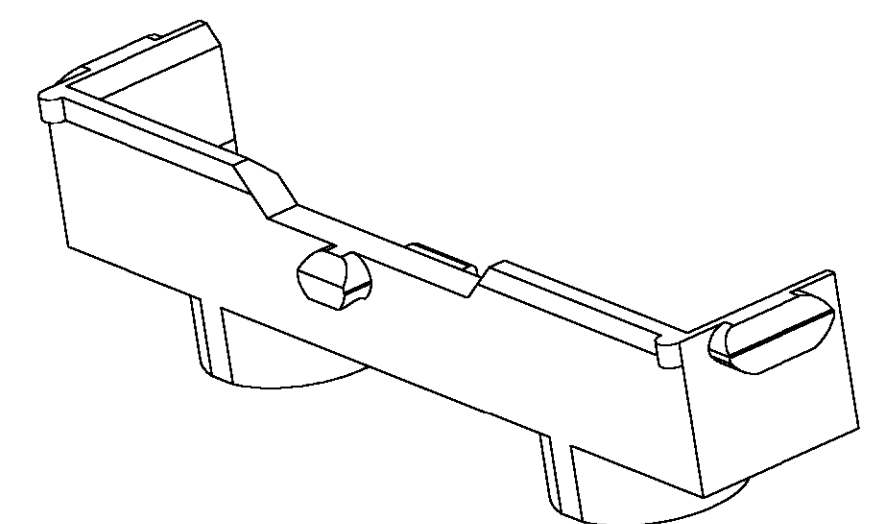
F  
E  
D  
C  
B  
A



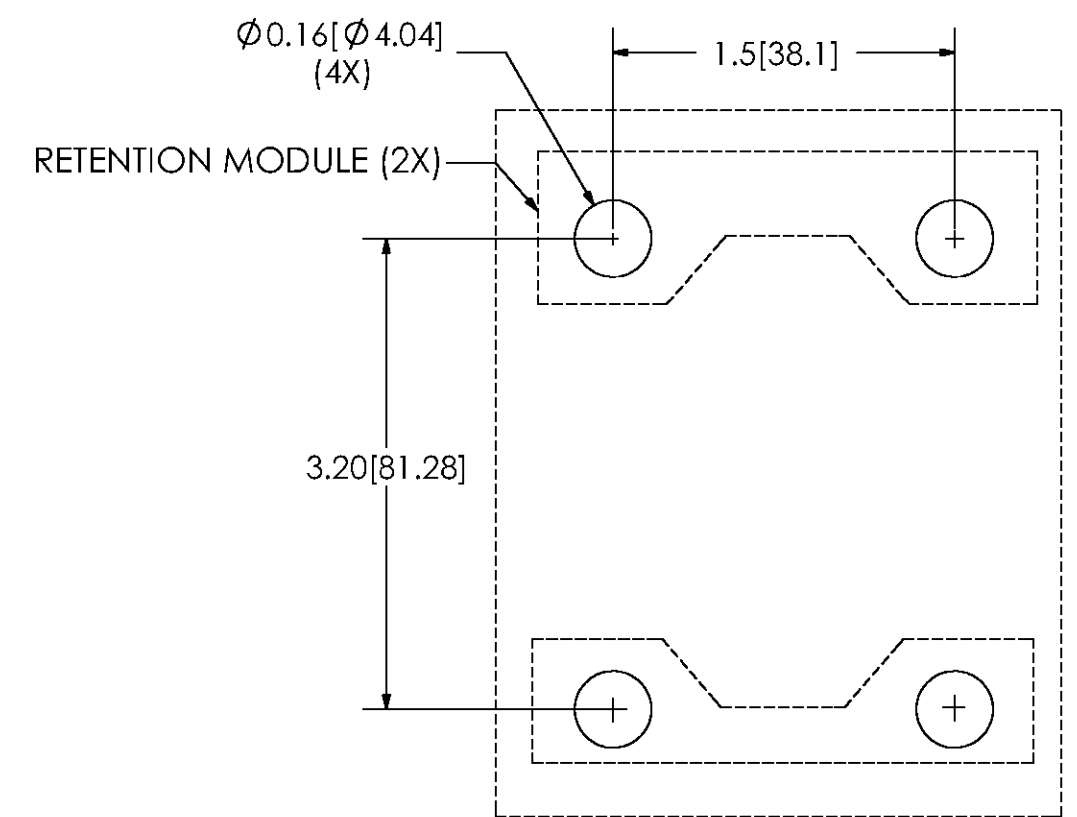
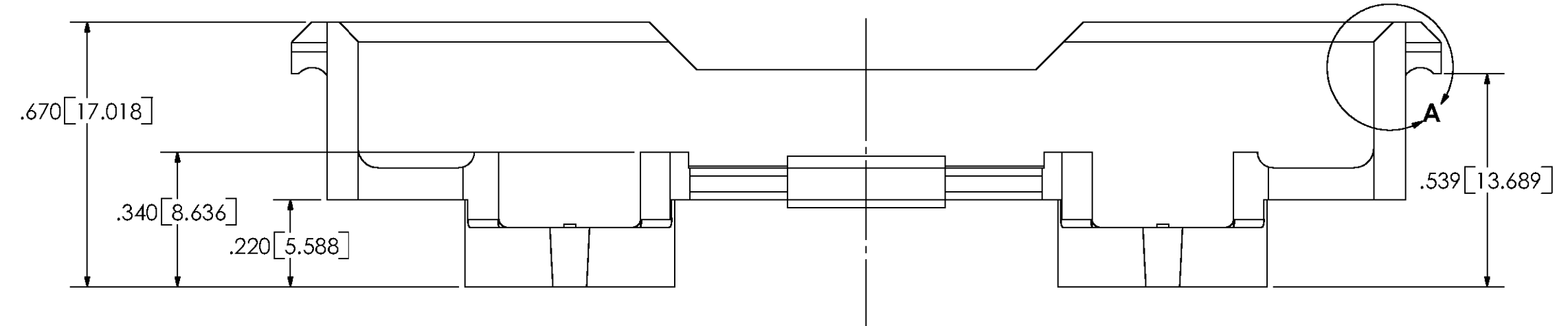
**DETAIL A  
SCALE= 8X**



**SCALE= 2X**



**SCALE= 2X**



**PCB LAYOUT  
REFERENCE DIMENSIONS FROM INTEL®  
DESIGN GUIDE**

**NOTES:**

- 1.) 2 RETENTION MODULES REQUIRED PER HEAT SINK.
- 2.) RETENTION MODULE USED WITH XEON PROCESSOR HEAT SINKS.
- 3.) QUICK RELEASE CLIP AVAILABLE FOR FLIP CHIP P/N: 9-1542007-7.

**CUSTOMER DRAWING**

SPECIFICATIONS ARE SUBJECT TO CHANGE WITHOUT NOTICE

REV.	REVISION INFO
A	RELEASE OS60-0045-03 E.TAO 04/09/03 APP'D: S.G 04/09/03
B	RELEASE OS60-0127-03 E.TAO 10/02/03 APP'D: A.M 10/02/03
C	RELEASE OS60-0061-03 E.TAO 03/11/04 APP'D: B.P 03/15/04
D	REVISED OS60-0214-04 E.TAO 8/23/04 APP'D: S.D 9/2/04

<b>DO NOT SCALE</b>	<b>tyco Electronics</b> Attleboro Falls Massachusetts 02763	
	UNLESS OTHERWISE SPECIFIED TOLERANCES ARE:	
	DRAWN BY: E.TAO	DATE: 03/07/03
	ENGINEER: S.G	DATE: 03/07/03
MATERIAL: LEXAN (BLACK) FLAMMABILITY: UL 94V-0	FINISH: -	
X ± .010 .XX ± .005 .XXX ± .005 FRACTIONS ± ANGLES ±1°	FILENAME: 9-1542007-5 PROJECT: - SYSTEM: SolidWorks	

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DIMENSIONS ARE IN: INCHES [MM]	SCALE: 3:1	TYCO PART NO: 9-1542007-5	SHEET 1 OF 1
TNIRD ANGLE PROJECTION	SIZE <b>C</b>	DWG. NO. C-9-1542007-5	REV <b>D</b>

8 7 6 5 4 3 2 1